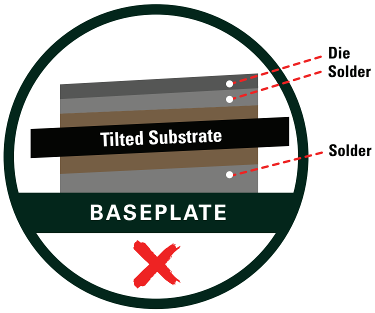
IMPROVED RELIABILITY PERFORMANCE

THE CHALLENGE:
Power Module Reliability

BAD COVERAGE = BAD PERFORMANCE

- ✗ Uneven bondline thickness
- ✗ Assembly tilt and variation
- ✗ Stress concentrations



- Reduced fatigue resistance ✗
- Premature lifecycle failures ✗

✗

Other Bondline Control Options

Few standoff points → Still risk of tilt
No reinforcement → Susceptible to movement
Potential solder creep → Process re-design

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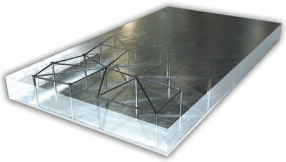
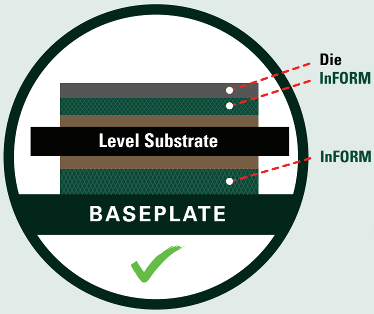
THE SOLUTION:
InFORMS® Technology



BONDLINE CONTROL = BEST PERFORMANCE

- ✓ Uniform bondline thickness
- ✓ Precise, repeatable assembly
- ✓ Even stress distribution



- Better fatigue resistance ✓
- 4X Extended lifecycle reliability performance ✓

InFORMS® are reinforced solder preforms that deliver a uniform bondline thickness after reflow

4X LONGER LIFECYCLE

✓

InFORMS® was developed to realize superior solder joint reliability in power module applications:

Standoff coverage across the entire assembly → Prevent tilt and stress concentration
Integrated matrix adds strength → Solder creep resistance
Precise, repeatable bondline thickness → Consistent soldering performance during production
Wide range of alloys and configurations available → Drop-in replacement for solder preforms

Learn more: **www.indium.com**

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Form No. 99968 R0

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